



APA1606VRBXF/A-5MAV 1.6 x 0.6 mm Right Angle SMD Chip LED Lamp

DESCRIPTIONS

- The source color devices are made with InGaN Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 1.6 x 1.2 x 0.6 mm right angle SMD LED, 0.6 mm thickness
- Low power consumption
- Wide viewing angle
- Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Tinned pads for improved solderability
- RoHS compliant

APPLICATIONS

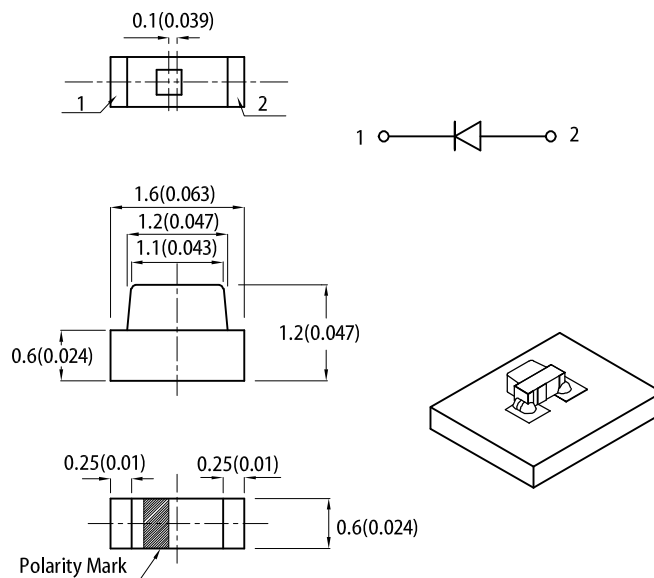
- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

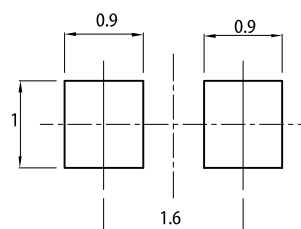


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 5mA ^[2]			Viewing Angle ^[1]
			Code.	Min.	Max.	2θ1/2
APA1606VRBXF/A-5MAV	■ Blue (InGaN)	Yellow Fluorescent	U	50	80	110°
			V	80	120	
			W	120	180	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value			Unit
			Min.	Typ.	Max.	
Chromaticity Coordinates x I _F = 5mA	x ^[1]	Blue	-	0.20	-	-
Chromaticity Coordinates y I _F = 5mA	y ^[1]	Blue	-	0.15	-	-
Capacitance	C	Blue	-	100	-	pF
Forward Voltage I _F = 5mA	V _F ^[2]	Blue	2.5	-	2.6	V
			2.6	-	2.7	
			2.7	-	2.8	
			2.8	-	2.9	
			2.9	-	3.0	
			3.0	-	3.1	
Reverse Current (V _R = 5V)	I _R	Blue	-	-	50	uA
Temperature Coefficient of x I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _x	Blue	-	-0.15	-	10 ⁻³ /°C
Temperature Coefficient of y I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _y	Blue	-	-0.18	-	10 ⁻³ /°C
Temperature Coefficient of V _F I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _V	Blue	-	-3	-	mV/°C

Notes:

1. Measurement tolerance of the chromaticity coordinates is ±0.01.
2. Forward voltage: ±0.1V.
3. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

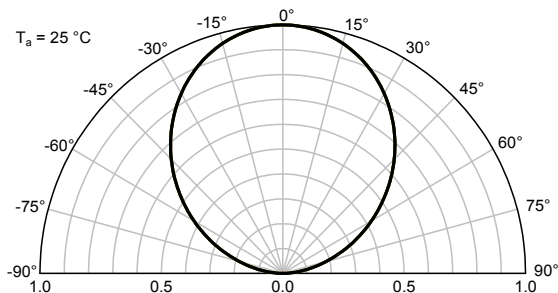
Parameter	Symbol	Value	Unit
Power Dissipation	P _D	120	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	100	mA
Electrostatic Discharge Threshold (HBM)	-	250	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	395	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	290	°C/W

Notes:

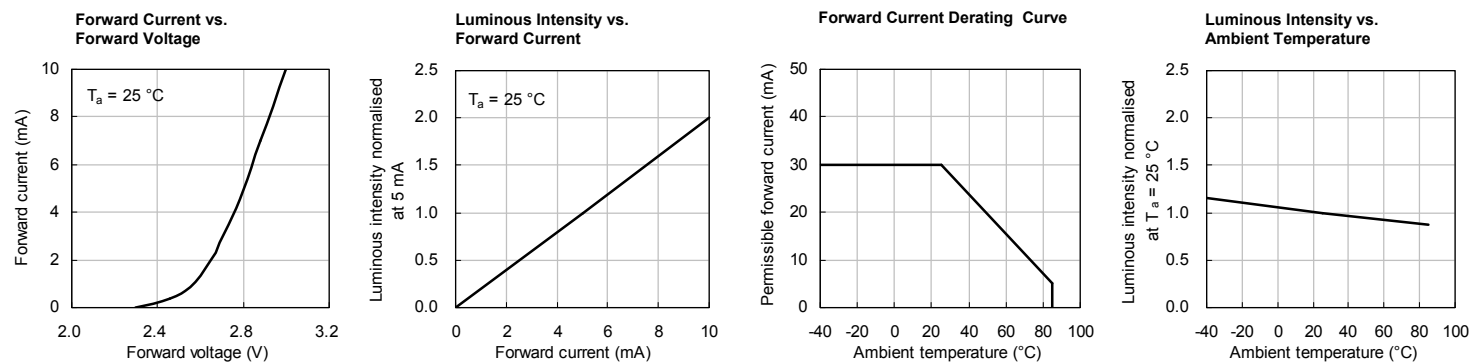
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

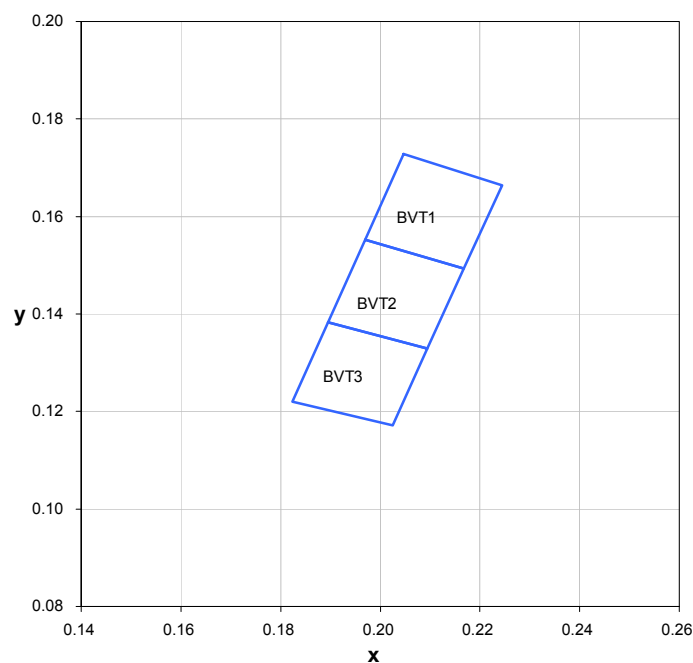
SPATIAL DISTRIBUTION



BLUE



CIE CHROMATICITY DIAGRAM

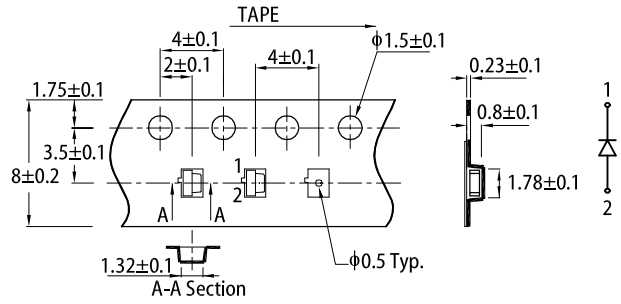
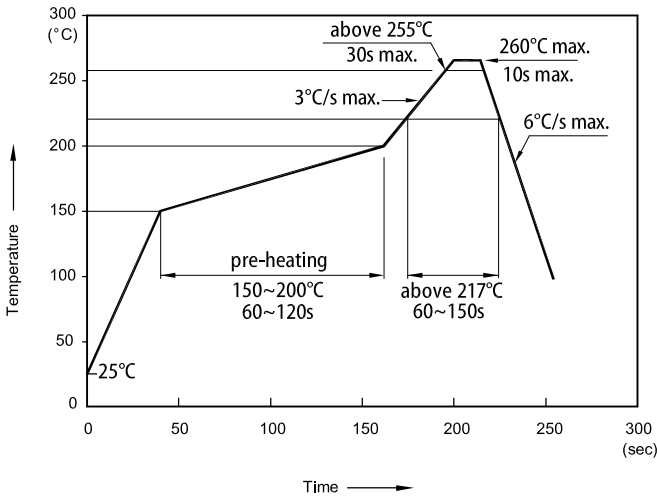


	x	y
BVT1	0.2047	0.1728
	0.1970	0.1552
	0.2168	0.1493
	0.2244	0.1663
BVT2	0.1970	0.1552
	0.1895	0.1383
	0.2095	0.1330
	0.2168	0.1493
BVT3	0.1895	0.1383
	0.1824	0.1221
	0.2025	0.1172
	0.2095	0.1330

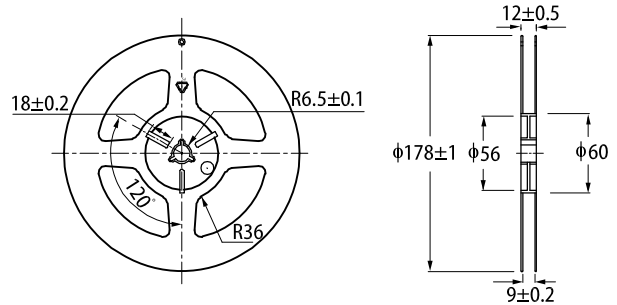
Notes:
 Shipment may contain more than one chromaticity regions.
 Orders for single chromaticity region are generally not accepted.
 Measurement tolerance of the chromaticity coordinates is ± 0.01 .

REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

TAPE SPECIFICATIONS (units : mm)



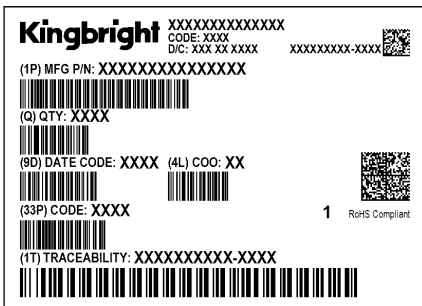
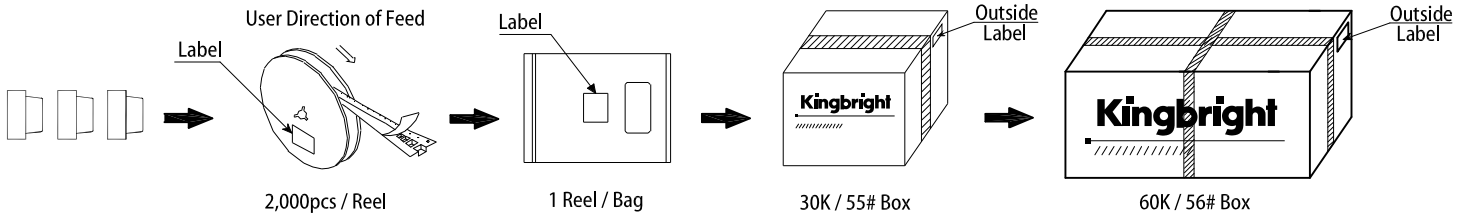
REEL DIMENSION (units : mm)



Notes:

1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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